

TO-1615BC-MRPBFGF-N

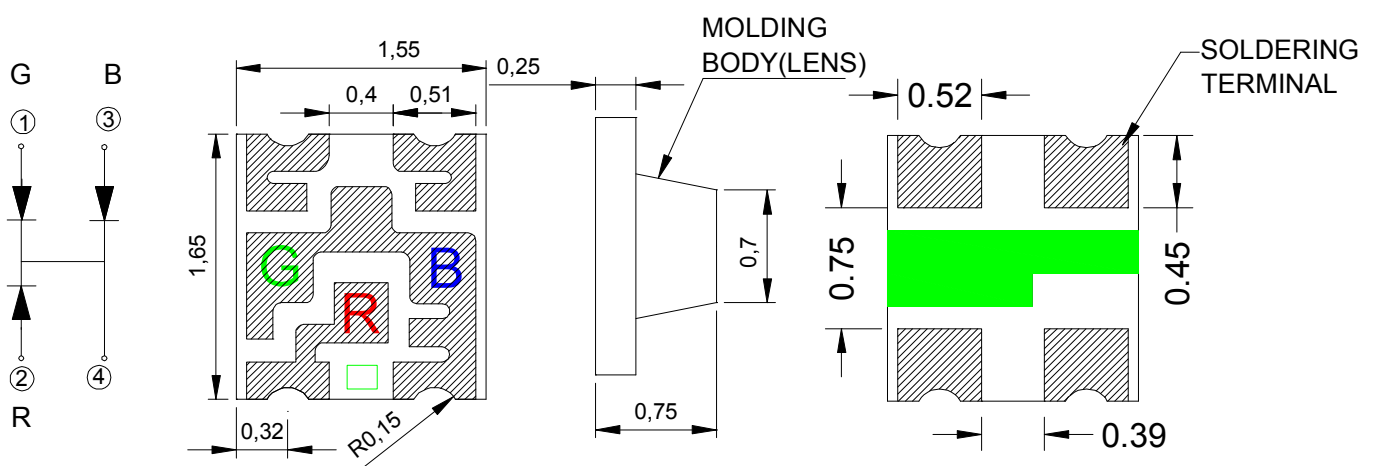
Surface Mount Device LED

Part Number	Chip		Lens Color
	Material	Source Color	
TO-1615BC-MRPBFGF-N	AlGaInP	Red	Water Clear
	InGaN	Green	
	InGaN	Blue	

Features

- IC compatible
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow soldering process
- Top view type
- Pack in 8 mm tape on 7" diameter reel
- RoHS compliant
- Moisture sensitivity Level: level 3

Dimensions



Notes:

1. All dimensions are in millimeter.
2. Tolerance is ± 0.1 mm unless individual mark noted.

Absolute Maximum Rating @ Ta=25°C

Parameter	Maximum Rating			Unit
	MR	P	B	
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	80	80	80	mA
Power Dissipation	75	105	105	mW
Continuous Forward Current	25	25	25	mA
Reverse Voltage	5	5	5	V
Operating Temperature Range	-55°C to +85°C			
Storage Temperature Range	-55°C to +105°C			
IR Reflow Soldering Profile For Lead Free Soldering	260°C			

Electrical / Optical Characteristic @ Ta=25°C

Parameter	Symbol	MR			P			B			Unit	Test Condition
		Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.		
Luminous Intensity	Iv	190		542	417		917	146		417	mcd	I _F =20mA
Viewing Angle	2θ1/2		130			130			130		deg	I _F =20mA
Forward Voltage	V _F		1.9			3.3			3.3		V	I _F =20mA
Dominant Wavelength	λ _d		630			525			468		nm	I _F =20mA
Spectral Line Half-Width	Δλ		17			36			26		nm	I _F =20mA
Reverse Current	I _R			10			10			10	μA	V _R =5V

Bin Code List for Reference

MR:

Luminous Intensity		Unit : mcd@20mA
Bin Code	Min	Max
F2	190	247
F3	247	321
F4	321	417
G1	417	542

P:

Luminous Intensity		Unit : mcd@20mA
Bin Code	Min	Max
G1	417	542
G2	542	705
G3	705	917

B:

Luminous Intensity		Unit : mcd@20mA
Bin Code	Min	Max
F1	146	190
F2	190	247
F3	247	321
F4	321	417

Tolerance of Luminous Intensity on each bin is $\pm 15\%$